

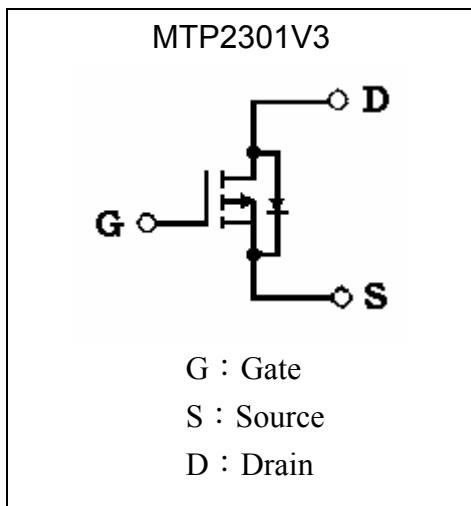
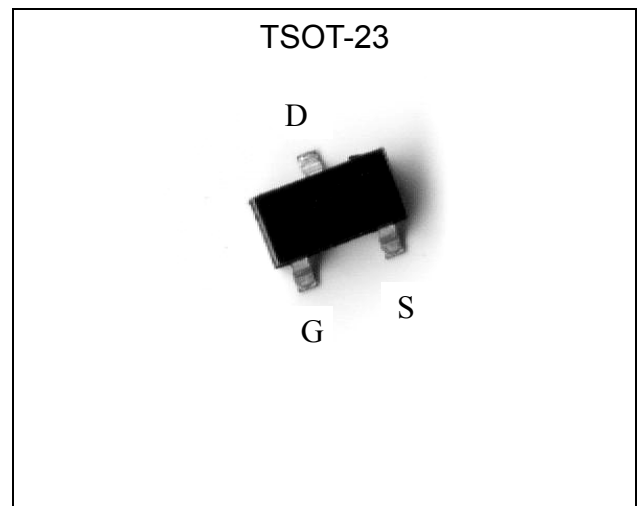
-20V P-CHANNEL Enhancement Mode MOSFET

MTP2301V3

BV_{DSS}	-20V
I_D	-3.4A
$R_{DS(on)(MAX)}@V_{GS}=-4.5V, I_D=-2.8A$	79m Ω (typ.)
$R_{DS(on)(MAX)}@V_{GS}=-2.5V, I_D=-2A$	116m Ω (typ.)

Features

- Advanced trench process technology
- High density cell design for ultra low on resistance
- Excellent thermal and electrical capabilities
- Compact and low profile TSOT-23 package
- Pb-free lead plating and halogen-free package

Equivalent Circuit

Outline

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V _{DS}	-20	V
Gate-Source Voltage		V _{GS}	±8	V
Continuous Drain Current @T _A =25°C, V _{GS} =-4.5V		I _D	-3.4	A
Continuous Drain Current @T _A =70°C, V _{GS} =-4.5V			-2.7	
Pulsed Drain Current		I _{DM}	-10	
Maximum Power Dissipation	T _a =25°C	P _D	1.38 (Note)	W
	T _a =70°C		0.88 (Note)	
Operating Junction and Storage Temperature Range		T _j ; T _{stg}	-55~+150	°C



Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient(PCB mounted)	Rth,ja	90 (Note)	°C/W
Lead Temperature, for 5 second soldering(1/8" from case)	T _L	260	°C

Note : Surface mounted on 1 in ²FR-4 board with 2 oz. copper, t ≤ 5sec; 270 °C/W when mounted on minimum copper pad.

Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-20	-	-	V	V _{GS} =0, I _D =-250μA
V _{GS(th)}	-0.45	-	-	V	V _{DS} =V _{GS} , I _D =-250μA
I _{GSS}	-	-	±100	nA	V _{GS} =±8V, V _{DS} =0
I _{DSS}	-	-	-1	μA	V _{DS} =-16V, V _{GS} =0
*R _{DS(ON)}	-	79	100	mΩ	I _D =-2.8A, V _{GS} =-4.5V
	-	116	150		I _D =-2A, V _{GS} =-2.5V
*G _{FS}	-	6.3	-	S	V _{DS} =-5V, I _D =-2.8A
Dynamic					
C _{iss}	-	446	-	pF	V _{DS} =-10V, V _{GS} =0, f=1MHz
C _{oss}	-	57	-		
C _{rss}	-	52	-		
t _{d(ON)}	-	9.2	20	ns	V _{DD} =-10V, I _D =-1A, R _L =6Ω, V _{GEN} =-4.5V, R _G =6Ω
t _r	-	7.3	60		
t _{d(OFF)}	-	38	50		
t _f	-	12	20		
Q _g	-	3	10	nC	V _{DS} =-10V, I _D =-3A, V _{GS} =-2.5V,
Q _{gs}	-	0.8	-		
Q _{gd}	-	1.1	-		
Source-Drain Diode					
I _S	-	-	-1.6	A	-
V _{SD}	-	-0.86	-1.2	V	V _{GS} =0V, I _S =-1.6A
trr*	-	30	-	ns	I _F =-3A, dI _F /dt=100A/μs
Qrr*	-	25	-	nC	

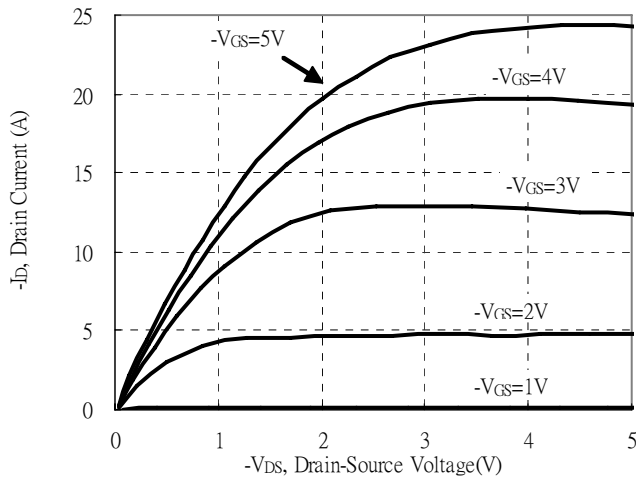
*Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

Ordering Information

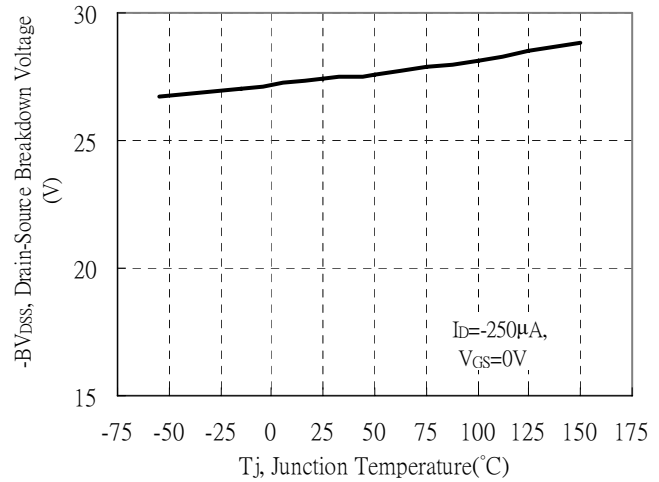
Device	Package	Shipping	Marking
MTP2301V3	TSOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel	01

Typical Characteristics

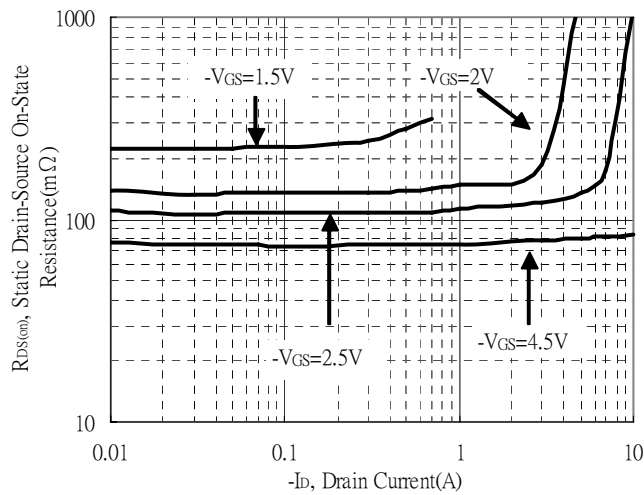
Typical Output Characteristics



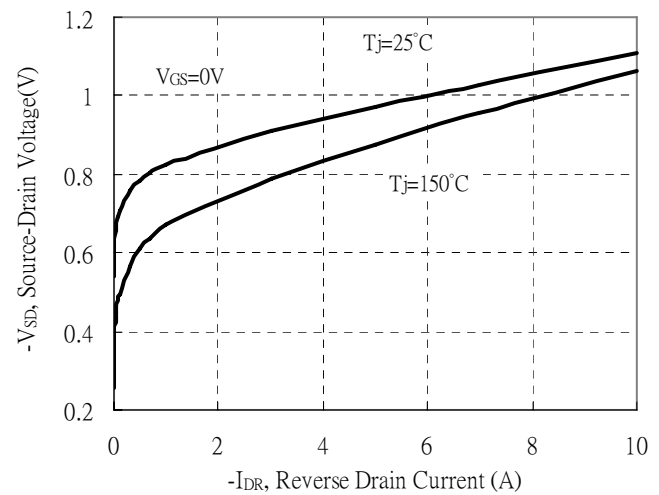
Brekdown Voltage vs Ambient Temperature



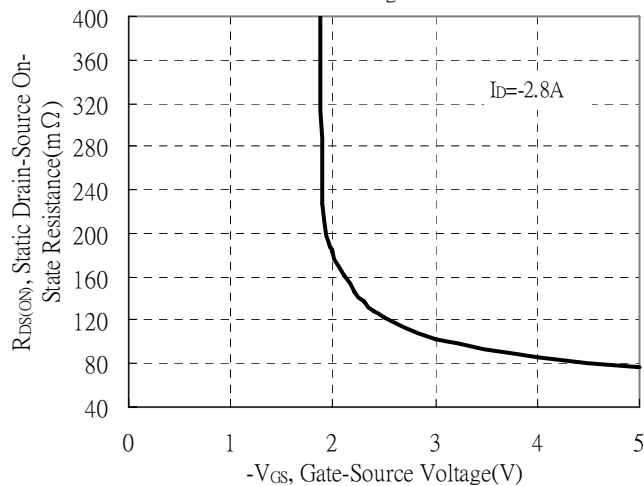
Static Drain-Source On-State resistance vs Drain Current



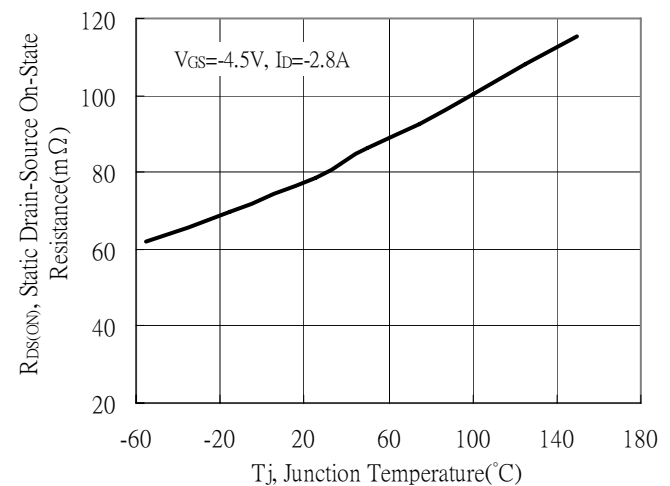
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

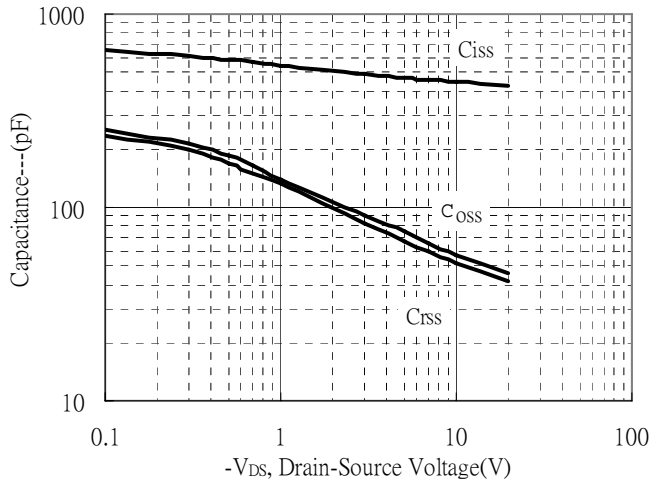


Drain-Source On-State Resistance vs Junction Temperature

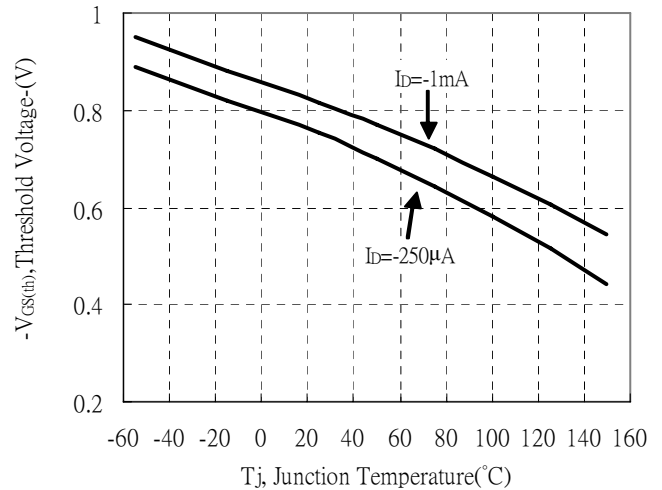


Typical Characteristics(Cont.)

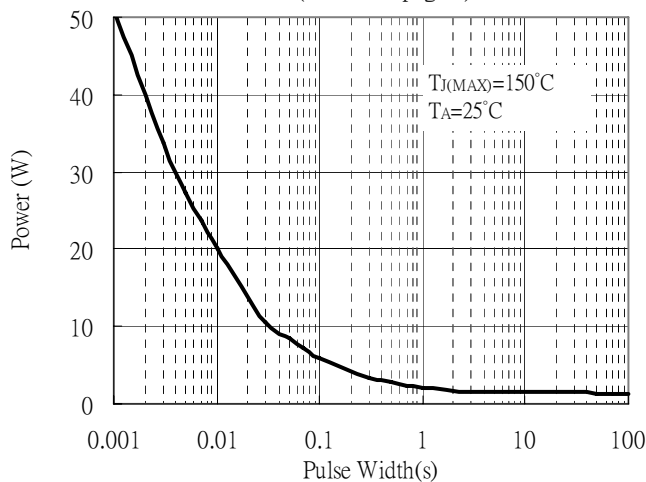
Capacitance vs Drain-to-Source Voltage



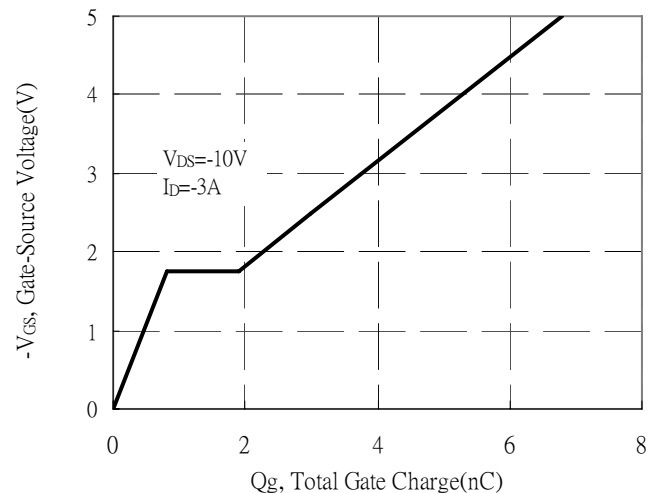
Threshold Voltage vs Junction Temperature



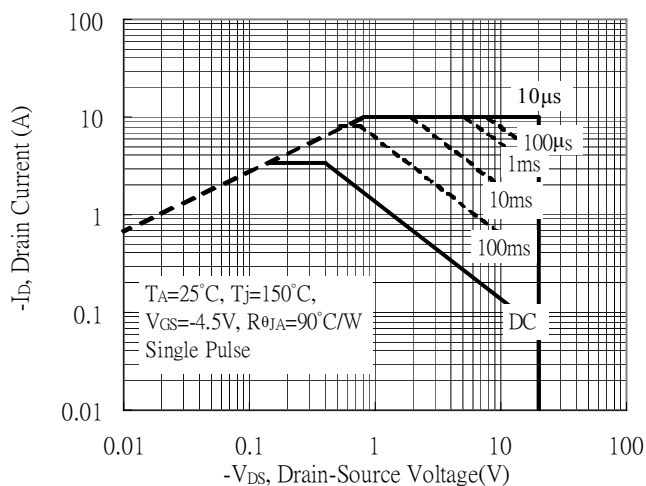
Single Pulse Power Rating, Junction to Ambient
 (Note 1 on page 2)



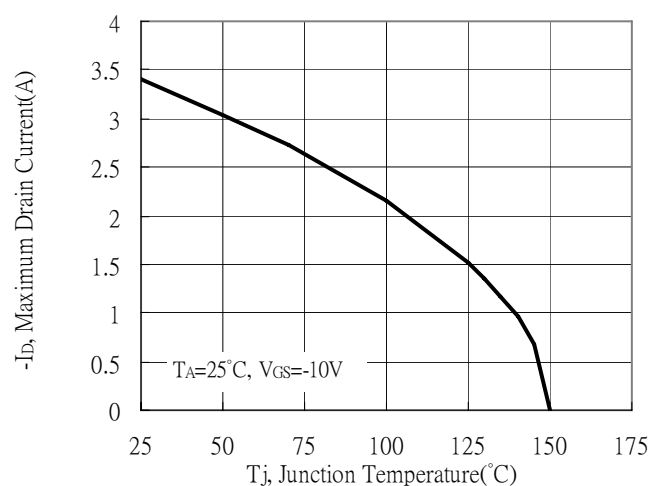
Gate Charge Characteristics



Maximum Safe Operating Area

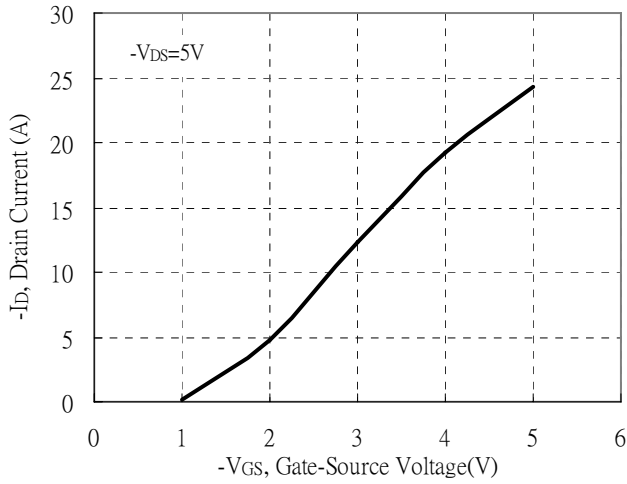


Maximum Drain Current vs Junction Temperature

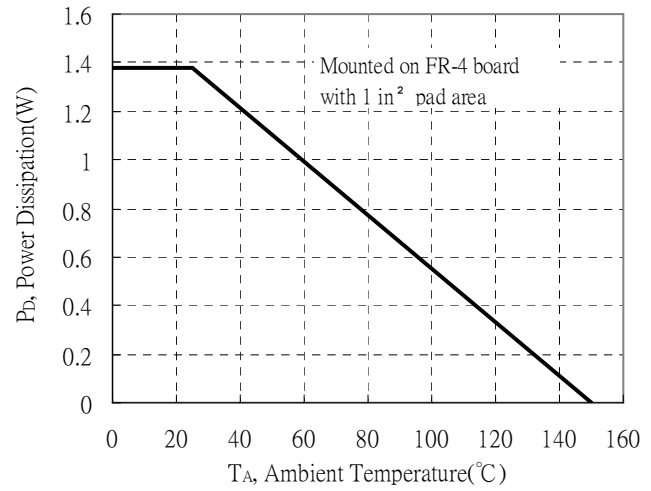


Typical Characteristics(Cont.)

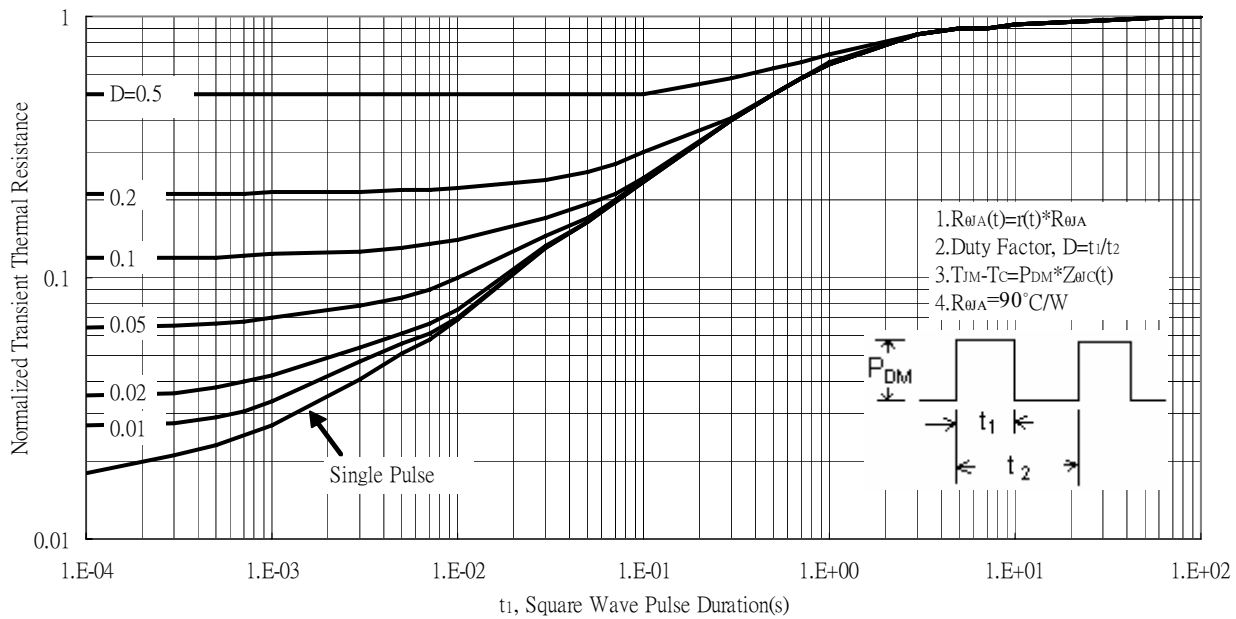
Typical Transfer Characteristics



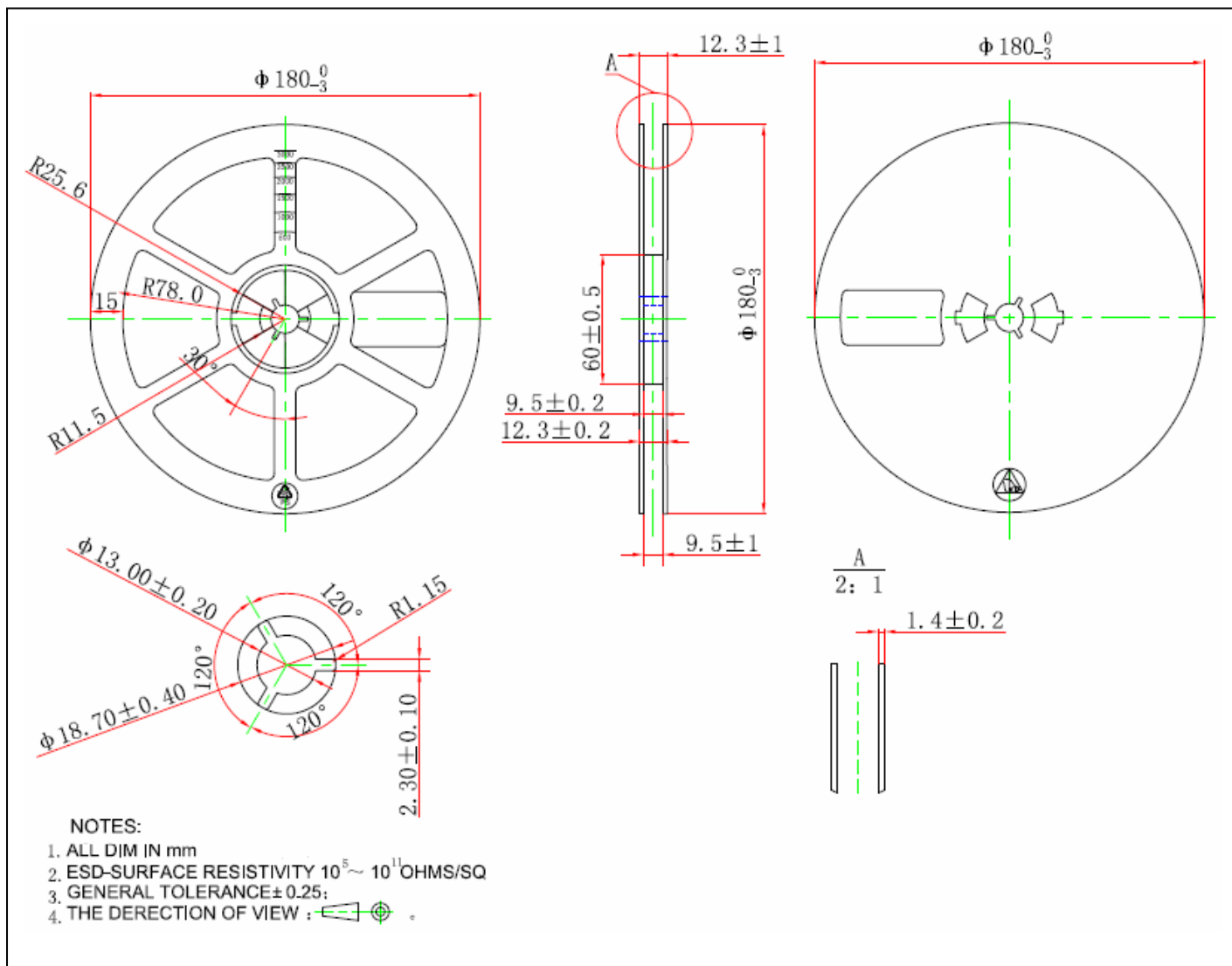
Power Derating Curve



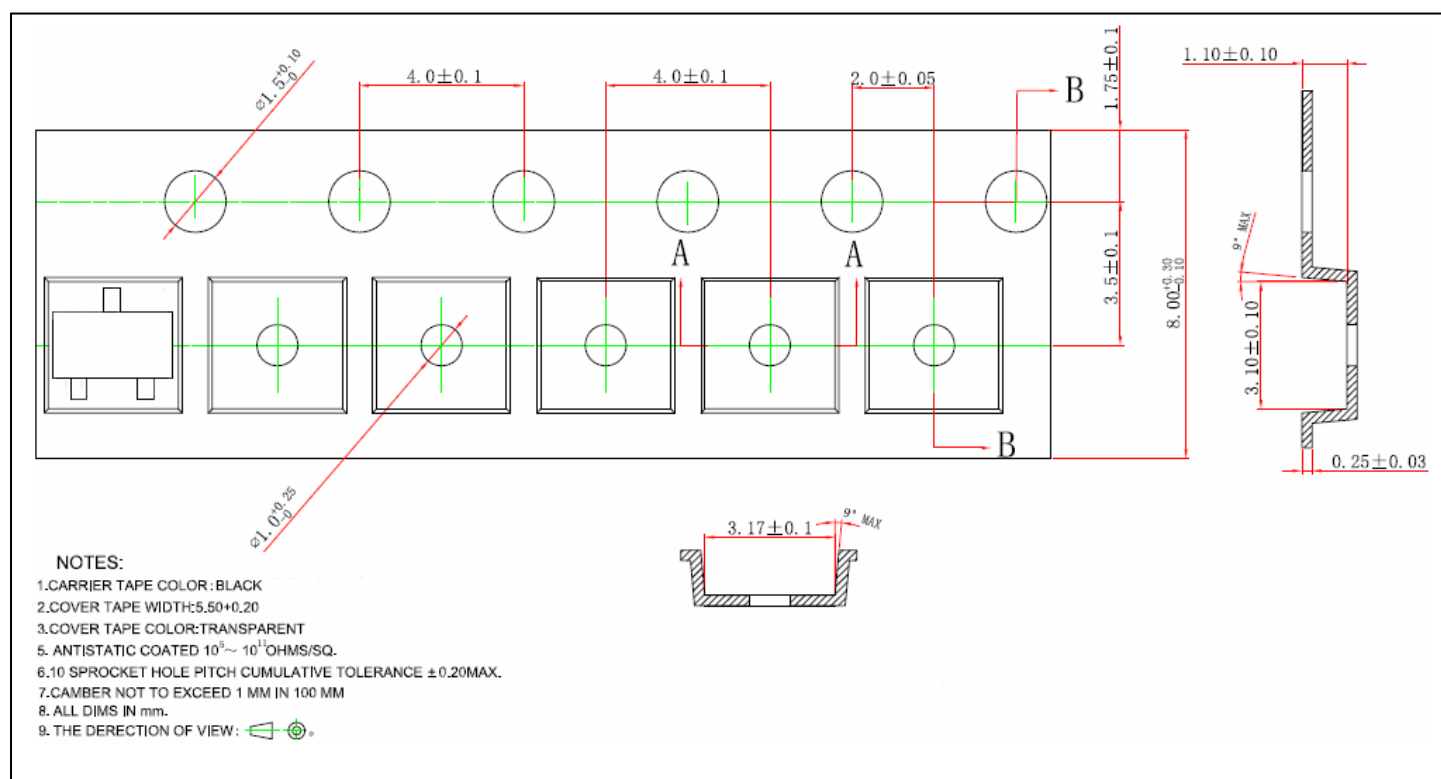
Transient Thermal Response Curves



Reel Dimension



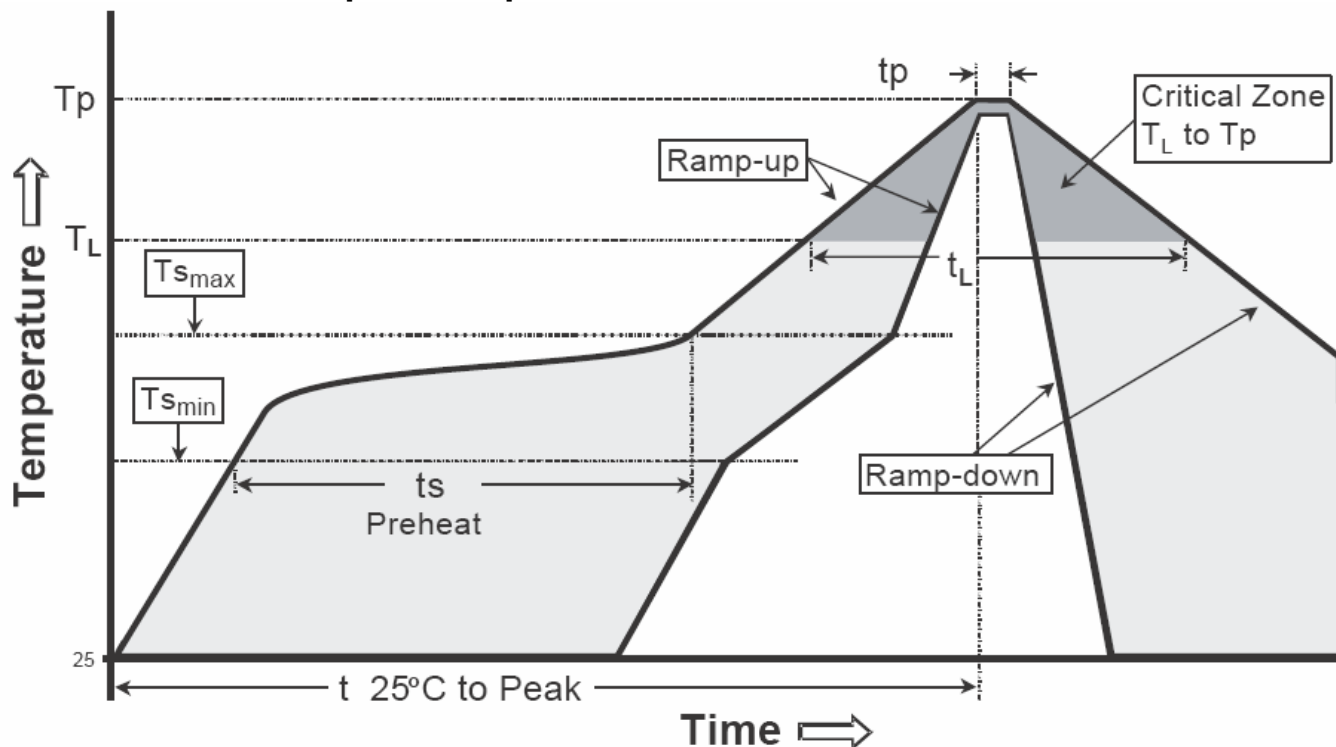
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

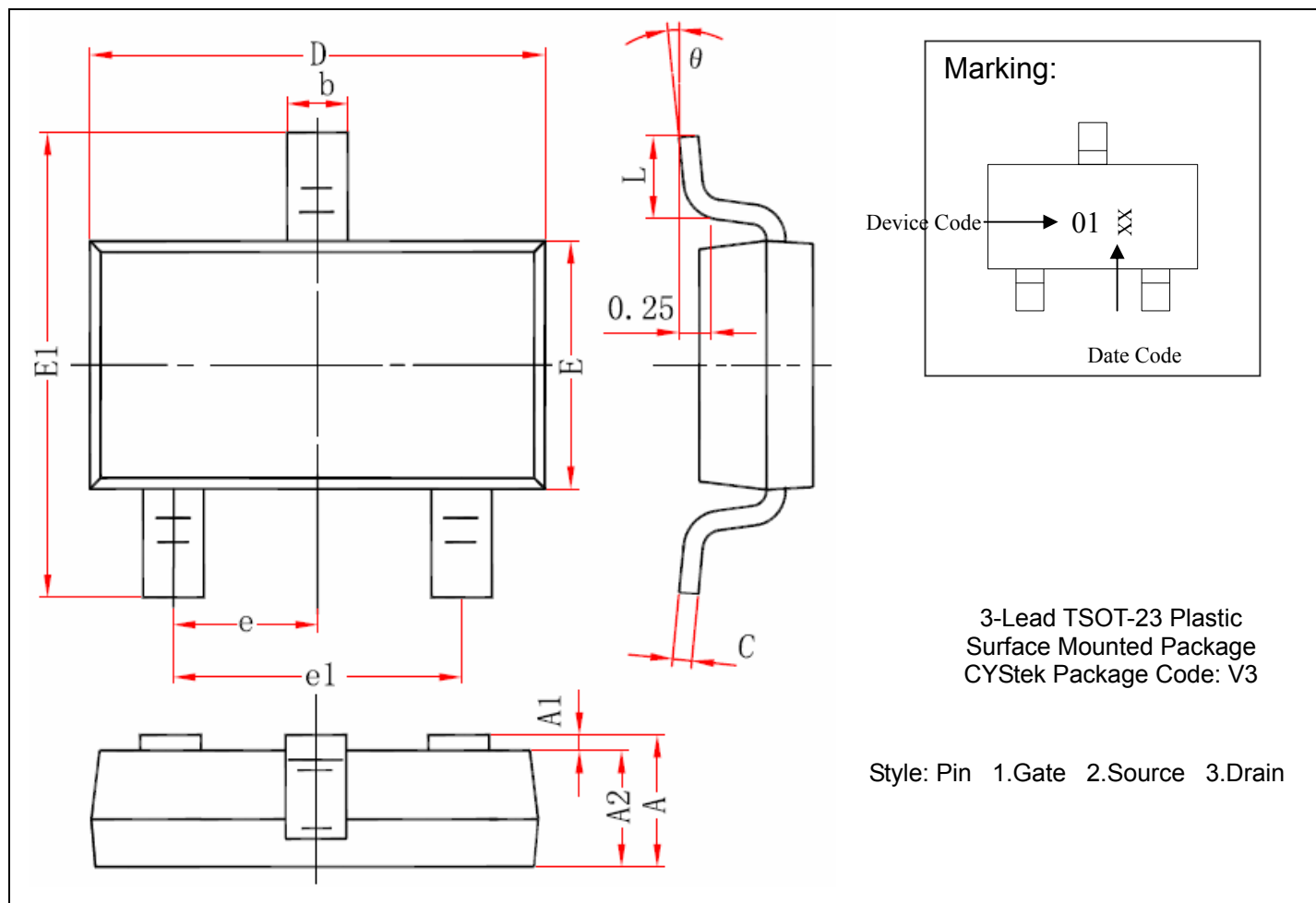
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (TL)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TSOT-23 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.028	0.035	0.700	0.900	E	0.063	0.067	1.600	1.700
A1	0.000	0.004	0.000	0.100	E1	0.104	0.116	2.650	2.950
A2	0.028	0.031	0.700	0.800	e	0.037(BSC)		0.95(BSC)	
b	0.014	0.020	0.350	0.500	e1	0.075(BSC)		1.90(BSC)	
c	0.003	0.008	0.080	0.020	L	0.012	0.024	0.300	0.600
D	0.111	0.119	2.820	3.020	θ	0°	8°	0°	8°

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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